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Transmitted herewith for filing is the Patent Application of:

Inventor: JIN-YUAN LEE

For: A THERMALLY COMPLIANT PCB SUBSTRATE FOR THE APPLICATION OF CHIP SCALE PACKAGES

jc806 U.S. PTO



Enclosed are:

10/10/00

- ☒ 3 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to MEGIC Corp.
- ☒ Small Entity Status Form

JC947 U.S. PTO

09/684519



10/10/00

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 355.
TOTAL CLAIMS	73 -20=	53	x 9 =	\$ 477.
INDEP CLAIMS	2 -3=	0	x 40 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$832
			ASSIGNMENT	\$40.
			TOTAL	\$872.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$872. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761